ISMP 2025 Poster Presentaion | November 6th, 2025 (Thu) 13:10~14:00 | Happy Hall Lobby, Main Building 1F				
No.	**Reg.**	**Title**	**Name**	**Affiliation**
1. Design and Simulation				
P1-01	ABST-000197	Prevention of crack propagation in 2.5D glass interposers during RDL fabrication	LE XUAN-BACH	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY
P1-02	ABST-000121	Compact Heat-Dissipation in AoP with Thermal Vias and Perimeter-Wall Heat Spreader	SEO DEOK JIN	KOREA ELECTRONICS TECHNOLOGY INSTITUTE (KETI)
P1-03	ABST-000108	Design and Optimization of Stripline for High-Speed Signals	PARK KYONGNAM	KOREA ELECTRONICS TECHNOLOGY INSTITUTE (KETI)
P1-04	ABST-000081	Design of an N77 Band Hybrid Filter Combining Thin-Film SAW and Advanced Glass-IPD Technologies	PARK MINSOO	KOREA ELECTRONICS TECHNOLOGY INSTITUTE (KETI)
P1-05	ABST-000230	Effect of Forming Gas Annealing on a Fluorinated Silica Glass and Al2O3 for the Advanced Packaging	USTAD RUHAN	SEJONG UNIVERSITY
P1-06		Design of Passive IC Power Divider for X-band Low Earth Orbit Satellite Communication	KIM DAE-KWON	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY
P1-07	ABST-000136	A Dummy Bump-embedded Substrate Trace Design for Reduced Crosstalk of DRAM Filp-chip Package	KIM DONGUK	SUNGKYUNKWAN UNIVERSITY
P1-08	ABST-000224	Automated Pattern Generation for Machine Learning based thermal resistance equivalent modeling	CHOI JAEYOUNG	HANYANG UNIVERSITY
P1-09	ABST-000212	Enhancement of Heat Sink Thermal Performance through Surface Roughness Control Using 3D-Printed Mold with FDM Surface Patterns	JUNG MUGYEOM	HANYANG UNIVERSITY
P1-10	ABST-000201	Power Mapping of an NPU by experimental IR Thermography and Multiphysics Simulation	CHAI SUNGMO	POHANG UNIVERSITY OF SCIENCE AND TECHNOLOGY (POSTECH)
P1-11	ABST-000171	Heat Transfer Modeling for System-on-Chip using Finite Element Analysis: Experimental Validation and Deep Learning-based Approach for Acceleration	CHEON MIN JUN	HANBAT NATIONAL UNIVERSITY
P1-12	ABST-000164	Optimization of Low-Loss SiN MMI Couplers on Glass Substrates	LEE JIHYUN	HANYANG UNIVERSITY ERICA
P1-13	ABST-000157	Design of a Low-Loss SiN Evanescent Coupler for Co-Packaged Optics	SHIN SEOKYOUNG	HANYANG UNIVERSITY ERICA
P1-14	ABST-000111	Optical Coupling Structure for Co-Packaged Optics: Design and Simulation of SiON-Based Spot-Size Converter	JO KYUNGJIN	HANYANG UNIVERSITY ERICA
P1-15	ABST-000098	Machine Learning-Based Analysis of Mechanical Behavior and Microstructure Characterization	KANG SEONA	GYEONGKUK NATIONAL UNIVERSITY
P1-16	ABST-000075	Design of Low-Loss SiN Stitching Structures for Wafer-Level Optical Interconnects	YOON SEOKHYEON	HANYANG UNIVERSITY
P1-17	ABST-000158	Apodized Grating Design for High-Efficiency and Low-Loss Interlayer Grating Couplers	PARK SEUNGWOO	HANYANG UNIVERSITY ERICA
P1-18	ABST-000138	Palladium Plating Approach for Thermal Stress Reduction and Reliability Enhancement in Hybrid Bonding Interconnects	YOON CHANGMIN	HOSEO UNIVERSITY
P1-19	ABST-000114	Signal Integrity Performance Analysis of Silicon, Glass, and Organic Interposers Over Temperature Range	YI YERO	HONGIK UNIVERSITY
2. Packaging Process				
P2-01	ABST-000191	Machine Learning assisted Wedge Bonding Process Optimization	PARK BYUNG-GEON	KOREA INSTITUTE OF MACHINERY & MATERIALS
P2-02	ABST-000194	Comparison of the Surface Finish Properties and Bondability of ENEPIG and Nickel-less DEG and EPIG	LIM JIHO	MK CHEM & TECH
P2-03	ABST-000092	Fabrication of Glass-Si Hermetic Package Using Au-Sn Eutectic Bonding with TGV Process for 6G Upper Mid-Band Applications	MIN HYOJEONG	KOREA ELECTRONICS TECHNOLOGY INSTITUTE(KETI)
P2-04	ABST-000087	Reliability Verification of Multi-Layer Daisy Chain Test Structures Through Layer-by-Layer Electrical Measurement	CHO YOUNGBEEN	KOREA ELECTRONICS TECHNOLOGY INSTITUTE(KETI)
P2-05	ABST-000079	Enhancing Bonding Stability in Double-Sided Flip-Chip on Glass through Load Limiting and Thermal Spreading	HAN JEONGIN	KOREA ELECTRONICS TECHNOLOGY INSTITUTE(KETI)
P2-06	ABST-000076	Mitigation of Tear-Drop Via Plating Defects in Build-Up Dielectrics Using Top-Side Multi-Step Laser Drilling	SEO MIRAE	KOREA ELECTRONICS TECHNOLOGY INSTITUTE(KETI)
P2-07	ABST-000060	Electroless Plating of Fe-Ni-B Alloy on Glass Substrates	KANG NA-YOUNG	HONGIK UNIVERSITY
P2-08	ABST-000043	Embedded MEMS Cs Vapor Cell Package with Optical Mount Compatibility for Spontaneous Four-Wave Mixing in Quantum Optics	NA YEEUN	NATIONAL NANO FAB CENTER
P2-09	ABST-000232	BEOL-Compatible Magnesium Fluoride Diffusion Barriers for Preventing Copper Migration in Si/SiO2 Structures	KAMBLE TUSHAR	SEJONG UNIVERSITY
P2-10	ABST-000213	Enhancement of Seed Layer Adhesion on Glass Substrates via ALD-Deposited High-k Thin film	KIM SUNBUM	HANYANG UNIVERSITY

P2-11	ABST-000167	Comparative Evaluation of Multi-Reflow Laser and Conventional Soldering for Reliability Improvement in MLCC Assembly	IM TAEYOON	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)
P2-12	ABST-000135	Strengthening SiO_2 Bonding Reliability in Hybrid Bonding through Plasma Process and Queue Time Control	KIM INJOO	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY
P2-13	ABST-000105	Improved Thermal Management in IC Packages Using Boron Carbide-Reinforced Epoxy Composites	AL SALIM ABDALLAH	SUNGKYUNKWAN UNIVERSITY
P2-14	ABST-000183	Dielectric Bonding Method for 3D Integration Packaging Using Self-Assembled Monolayer	CHOI SUNGJAE	SEOUL NATIONAL UNIVERSITY
P2-15	ABST-000149	FEM Simulation for Warpage Prediction with Process Stage –Dependent Material Properties during FCBGA Packaging Process	LEE SEONDO	KOREA ADVANCED INSTITUTE OF SCIENCE AND TECHNOLOGY (KAIST)
P2-16	ABST-000107	Hybrid Bonding Enabled by Nanoimprint Lithography of Polymeric Dielectric Layers	LEE SOHWI	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY
P2-17	ABST-000050	Advanced Cu Surface Modification Using Ar-CH4 Plasma Pre-treatment for Direct Bonding Applications	LEE HOOGWAN	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY
P2-18	ABST-000048	Polymer-Dependent Fly Cutting Process and Its Influence on Cu/Polymer Hybrid Bonding	JANG SUIN	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY
P2-19	ABST-000038	Low Thermal Budget Integration of High Temperature α-Ga_2O_3 layers onto Silicon Devices via Thermal Compression Bonding	LEE JIYUN	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY
P2-20	ABST-000036	Evaluation of Metal-Polymer Hybrid Bonding as an Alternative to Conventional Hybrid Bonding Interfaces	SUNG DONG YUN	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY
P2-21	ABST-000027	Reliability Analysis of Fine-Pitch Interconnections Using Epoxy-Based Laser-Bonding Materials with Different Glass Transition Temperatures.	LEE GA-EUN	ELECTRONICS AND TELECOMMUNICATIONS RESEARCH INSTITUTE (ETRI)
P2-22	ABST-000221	Selective IPL Soldering with Low Thermal Impact and Enhanced Joint Reliability	PARK YOUNG-JOO	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)
P2-23	ABST-000215	Cu/SiO_2 Hybrid Bonding with Cobalt Passivation for 3D Integration	LEE JAEHO	HANYANG UNIVERSITY
P2-24	ABST-000214	Characterization of PEALD SiNx Films for Dielectric-Dielectric Interface Applications	CHOI SEHYEON	HANYANG UNIVERSITY
P2-25	ABST-000184	Strain-Insensitive Interdigitated Capacitive Touch Screen Sensor with Porous Elastomer Substrate	KIM KYEONGTAE	HANYANG UNIVERSITY
P2-26	ABST-000180	Optimizing Thermal Interface Materials in Semiconductor Packages: Development of Alumina Filler	CHUNG YOON CHAN	INHA UNIVERSITY
P2-27	ABST-000156	Fabrication of Multi-Layer Cu RDLs on Glass Substrate	JIN HYEIN	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY
P2-28	ABST-000147	Reliability Analysis of Laser-Assisted Bonding with Compression (LABC) Using Non-Conductive Film (NCF) Containing Spherical h-BN Filler	KIM SEONG CHEOL	ELECTRONICS AND TELECOMMUNICATIONS RESEARCH INSTITUTE (ETRI)
P2-29	ABST-000140	Effect of soldering processes on IMC growth and mechanical reliability of SAC305/ENEPIG joints	LEE HYO-WON	CHUNGBUK NATIONAL UNIVERSITY
P2-30	ABST-000094	Fracture Behavior of ENEPIG/Sn–3.0Ag–0.5Cu Solder Joints Using Laser Assisted Bonding (LAB)	LEE TAE-HYEUN	GYEONGKUK NATIONAL UNIVERSITY & KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)
P2-31	ABST-000088	Influence of Silver Addition to Indium for Thermal Interface Material Joints with ENIG Coating on the Formation and Growth of Intermetallic Compounds	SIM YUNSUB	CHOSUN UNIVERCITY
P2-32	ABST-000086	Low Temperature Cu/SiO2 Hybrid Bonding Using Area-Selective Metal (Au) Passivation Technology for 3D IC and Advanced Packaging	JUNG HYUNJOON	SUNGKYUNKWAN UNIVERSITY
P2-34	ABST-000078	Development of W2W Hybrid Bonding for Sub-micron Pad	HA SEUNGYUN	NATIONAL NANO FAB CENTER
P2-35	ABST-000069	Transient Liquid Phase Bonding Using a Sn/2 μm Cu/Sn Laminated Solder Preform with Complete Consumption of the Cu Layer and High-Temperature Long-Term Reliability Evaluation	LEE DONG-BOK	CHUNGBUK NATIONAL UNIVERSITY
P2-36	ABST-000062	Improvement of Cu–Cu Bonding Properties using Ag Interlayer	BAEK SONGYEON	CHUNGBUK NATIONAL UNIVERSITY
P2-37	ABST-000057	Effect of Cu pillar micro-bump structures on the interfacial reaction kinetics in chip-to-chip bonded joints: reflow vs intense pulsed light (IPL) bonding	JANG EUNSU	CHUNGBUK NATIONAL UNIVERSITY
P2-38	ABST-000049	Effect of Dishing Depth and Process Parameters on Cu-to-Cu Bonding Recovery: A Simulation-to-Experiment Approach	OH SEUNGHWAN	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY
P2-39	ABST-000039	Formation and Optimization of Ru2Si3 Thin Films for Reduced Contact Resistance	CHOI SEOYEON	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY
P2-40	ABST-000015	Oxidation-Induced Head-in-Pillow Defects and a Rework Method in Sn-3.0Ag-0.5Cu BGA Packages	SHIN TAEK-SOO	SUNGKYUNKWAN UNIVERSITY
P2-41	ABST-000130	Finite Element Simulation of Laser-Induced Deep Etching Process for Through-Glass Via Formation	CHO MINSEO	HONGIK UNIVERSITY
P2-42	ABST-000165	Analysis of Indium Solder Joints in Laser-Assisted Bonding with Compression (LABC) via Reflow-Free Dipping Process	YOON MIRI	HANBAT NATIONAL UNIVERSITY

P2-43	ABST-000162	Evaluation of Co-Co Direct Bonding at Low Temperatures for Hybrid Bonding Applications	KO SOOHYUN	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY
P2-44	ABST-000132	Polyimide Bonding Characteristics for Cu/Polymer Hybrid Bonding	YU JAEMIN	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY
P2-45	ABST-000061	Adhesion of Electroless-Plated Ni–P Alloy Seed Layers on Glass Substrates	PARK JINYOUNG	HONGIK UNIVERSITY
P2-46	ABST-000051	Geometry-Driven Effects of Cu Dishing and Cu Bonding Interface Integrity	SEO KANGMIN	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY
3. Substrate and Interposers				
P3-02	ABST-000228	Micro-crack free laser glass cutting and TGV for Advanced Semiconductor Packaging	PARK NAM-SON	TECH UNIVERSITY OF KOREA
P3-03	ABST-000226	Process Optimization of Fine-Pitch Flip-Chip Substrate Patterning for Ni-Less Surface Finish Evaluation at 25 µm Bump Pitch and 15 µm Line/Space	LEE TAE-YOUNG	TECH UNIVERSITY OF KOREA
P3-04	ABST-000175	Enabling Next-Generation Semiconductor Packaging with Glass-Core Substrate Process Innovations	LEE SEUNGYONG	LG INNOTEK
P3-05	ABST-000106	Improved removal of sputtered Ti/Cu seed layers using a combined wet and dry etching process for advanced interposer substrates	NOH JINMI	LG INNOTEK
P3-06	ABST-000071	Low-Dielectric SiO_2/Polyimide Prepreg Composite with Enhanced Interfacial, Thermal, and High-Frequency Properties	LEE DA YEONG	KOREA ELECTRONICS TECHNOLOGY INSTITUTE(KETI)
P3-07	ABST-000046	Fabrication of a 2-Layer RDL Structure with Sub-2µm L/S and 5µm Vias by Advanced Semi-Additive Process	LEE HAESEONG	KOREA ADVANCED NANO FAB CENTER (KANC)
P3-08	ABST-000030	Transmission loss characteristics according to thermal changes in an Au circuit formed on a glass wafer	IM YOUNGMIN	KOREA ELECTRONICS TECHNOLOGY INSTITUTE(KETI)
P3-09	ABST-000077	Silicon Nitride on Glass (SING) integrates compact, low-loss photonic routing with glass substrate scalability, enabling high-density optical redistribution layers for next-generation Co-Packaged Optics in high-performance computing and data-center applications	JIN TAEWON	HANYANG UNIVERSITY ERICA
P3-10	ABST-000234	Effects of Surface Roughness on the Mechanical and Optical Properties of Glass Interposers for 2.5D/3D HBM Packaging	HONG HYEYOUNG	SUNGKYUNKWAN UNIVERSITY
P3-11	ABST-000229	Control of Surface structuring for Through Glass Vias Using Femtosecond Laser Processing	LEE JAEBEOM	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)
P3-12	ABST-000146	Fabrication and Characterization of Polymer-based Multi-layer RDL for Interposer Applications	KANG MINJI	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY
P3-13	ABST-000139	Comparative analysis of thermal stress in TGV structures with various aspect ratios and glass materials	KIM KI-CHEOL	KANGNAM UNIVERSITY
P3-14	ABST-000126	Suppression of debris and residual stress in femtosecond laser processing of silicon wafer under low-temperature conditions	KIM TAESIK	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)
P3-15	ABST-000019	Numerical estimation of thermal resistance in package substrates with organic and glass cores	KIM TAEWOO	HANYANG UNIVERSITY
P3-16	ABST-000125	Finite Element Analysis of Porous Through-Glass Via Structures for Thermomechanical Reliability Enhancement in Glass Interposers	JEON JAEWOO	HONGIK UNIVERSITY
4. Devices and Components				
P4-01	ABST-000054	Continuous-Time Linear Equalization Based on Organic Mixed Ionic–Electronic Conductors	LEE YONGWOO	ULSAN NATIONAL INSTITUTE OF SCIENCE AND TECHNOLOGY (UNIST)
P4-02	ABST-000211	The study of Physical and Electrical Degradation of Film Capacitors Through High-Temperature and High-Humidity Conditions	JO EUNBYEOUL	KOREA AUTOMOTIVE TECHNOLOGY INSTITUTE (KATECH)
P4-03	ABST-000033	A Study on the isolation technique for AI automotive radar sensor with AiP	YEON KYUBONG	KOREA AUTOMOTIVE TECHNOLOGY INSTITUTE (KATECH)
P4-04	ABST-000032	A Study on the interference test systems for automotive 4D imaging radar with AoP	YEON KYUBONG	KOREA AUTOMOTIVE TECHNOLOGY INSTITUTE (KATECH)
P4-05	ABST-000031	A Study on the automotive semiconductor package with high reliability using virtual qualification technology	YEON KYUBONG	KOREA AUTOMOTIVE TECHNOLOGY INSTITUTE (KATECH)
P4-06	ABST-000181	Effect of CuO nanosheets addition on microstructure and mechanical properties of SnBiAg solder alloy	AVATARE AJAY	SEJONG UNIVERSITY
P4-07	ABST-000018	Thermal characterization of thermal interface materials under compression	SHIN CHAEEUN	HANYANG UNIVERSITY
P4-08	ABST-000101	Development of Silver EHD Jet Printing Design Rules for Reliable RF Component Fabrication	KIM HYEONGJUN	ULSAN NATIONAL INSTITUTE OF SCIENCE AND TECHNOLOGY (UNIST)
P4-09	ABST-000100	Radio-Frequency Carbon Nanotube Field-Effect Transistors on Glass Substrates	EUM SUNGMIN	ULSAN NATIONAL INSTITUTE OF SCIENCE AND TECHNOLOGY (UNIST)
5. Materials Technology				
P5-01	ABST-000189	Material Optimization of Back Grinding Tape to Prevent Die Chipping	SEO KI-SEUNG	LG CHEM
P5-02	ABST-000104	Pressureless Sinter-Bonding Characteristics of Ag Nanopaste Formulated with Ag Complex Ink	PARK CHANGSU	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY

P5-03	ABST-000029	Dielectric properties of low-k FPC substrate materials utilizing AAO	IM YOUNGMIN	KOREA ELECTRONICS TECHNOLOGY INSTITUTE (KETI)
P5-04	ABST-000182	Electrodeposition of Large-Grain Cu(111) Film using Reducing Agent for Electromigration Resistant Applications	KIM SOOJIN	HANYANG UNIVERSITY
P5-05	ABST-000016	Development of High Thermal Conductivity and Low Viscosity Underfill Material Using Shape Memory Polymer Composite Particles	LEE MINGEUN	KOREA ADVANCED INSTITUTE OF SCIENCE AND TECHNOLOGY
P5-06	ABST-000010	Measurement of dielectric bonding adhesion energy with machine compliance correction by DCB test	KIM DONG-HYEON	ULSAN NATIONAL INSTITUTE OF SCIENCE AND TECHNOLOGY (UNIST)
P5-07	ABST-000150	High-Performance Polyimide Films Containing Benzocyclobutene Moieties for Advanced Microelectronics Packaging	SAJJAD LARAIB	SEJONG UNIVERSITY
P5-08	ABST-000052	Study on the joint properties of Sn-3.0Ag-0.5Cu solder with nm-thick Al2O3 layer	NOH EUN-CHAE	CHUNGBUK NATIONAL UNIVERSITY
P5-09	ABST-000113	Nanoindentation Creep Behavior of Sn-Bi Based Alloys by Zn Addition	KAWAKAMI NATSUKI	THE UNIVERSITY OF OSAKA
P5-10	ABST-000093	Thermal Property Evaluation of Lotus-type Porous Cu/Solder Composite Joints	HIRASE KANA	THE UNIVERSITY OF OSAKA
P5-11	ABST-000083	In-situ Study on the Stress-Temperature Characteristics of Cu/Photosensitive Polyimide (PSPI) Thin Films for FOWLP	KWON HYUKJIN	GYEONGKUK NATIONAL UNIVERSITY
P5-12	ABST-000082	Effect of N2 Plasma Treatment on the Interfacial Adhesion Energy of Dielectric-Dielectric Bonding for Low-Temperature Hybrid Bonding	EOM YEONGHEUM	GYEONGKUK NATIONAL UNIVERSITY
P5-13	ABST-000080	Post-Bond Annealing Effect on the Quantitative Interfacial Adhesion Energy of SiO2-SiO2 Interfaces for Low-Temperature Hybrid Bonding	JUNG YEONWOO	GYEONGKUK NATIONAL UNIVERSITY
P5-14	ABST-000059	Sputter-Engineered PVD SiCN as a Low-k Dielectric for Hybrid Cu Bonding	CHOI JUNYOUNG	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY
P5-15	ABST-000216	Enhanced hydrophobicity of MgO as a Thermal Management Filler for Battery	JUN YUEUN	DONGGUK UNIVERSITY
P5-16	ABST-000203	Electroplating of Copper with Conductive Nanomaterials for Enhanced TSV Reliability	PARK JEONGWOO	HANYANG UNIVERSITY
P5-17	ABST-000188	Thickness-dependent Resistivity of Ultrathin Topological Semimetal MoP for Next-generation Interconnect in BEOL	SHIN YEJI	POHANG UNIVERSITY OF SCIENCE AND TECHNOLOGY (POSTECH)
P5-18	ABST-000187	Low-overpotential Electrodeposition of submicrometer-scale Cu Single Crystal	JEONG GIHO	POHANG UNIVERSITY OF SCIENCE AND TECHNOLOGY (POSTECH)
P5-19	ABST-000179	Developing High-Thermal-Conductivity Epoxy Composites: Hybrid Fillers of Silica Nanowires and Alumina-Coated Core–Shell Nanoparticles	PARK MINAH	INHA UNIVERSITY
P5-21	ABST-000173	Cuticular pad–inspired selective frequency damper for nearly dynamic noise–free bioelectronics	SHIM JAE SEUNG	SUNGKYUNKWAN UNIVERSTIY
P5-22	ABST-000154	Anisotropic, Highly Thermally Conductive hBN–Fe3O4 Fiber/Epoxy Composites via Magnetic Alignment	JEONG YEONWOOK	SUNGKYUNKWAN UNIVERSITY
P5-23	ABST-000145	Electrospun h-BN/PAN Hybrid Carbon Fibers for High-Performance Thermal Interface Materials in Advanced Electronic Packagingckaging	CHOI HO JEONG	SUNGKYUNKWAN UNIVERSITY
P5-24	ABST-000144	Anisotropic Thermal Interface Composites Based on Electric-Field-Aligned $BaTiO_3$ Fibers	OH BO GYEONG	SUNGKYUNKWAN UNIVERSITY
P5-25	ABST-000143	Electroless Au Passivation for Oxidation-Free Cu–Cu Bonding	GO BYEONGCHAN	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY
P5-26	ABST-000090	Effect of Air Exposure Time after Two-step Ar/N_2 Plasma Treatment on the Interfacial Characteristics of the Cu-Cu Bonding Interface	LEE SEUNGGYUN	GYEONGKUK NATIONAL UNIVERSITY
P5-27	ABST-000068	Influence of TiC Nanoparticles and Soldering Process on the Microstructure and Mechanical Properties of Sn58Bi/Sn3.0Ag0.5Cu Hybrid Joints	LIM KWAN-SOO	CHUNGBUK NATIONAL UNIVERSITY
P5-28	ABST-000042	Bi-Directional Alignment of BN Micro-Platelets via Micro-Molding for Flexible, High-Performance Thermal Interface Materials	KIM YEJI	SUNGKYUNKWAN UNIVERSITY
P5-29	ABST-000026	PCLD as a Viscosity Modifier for Highly Filled Epoxy Composites	LIM YUMIN	INHA UNIVERSITY
P5-30	ABST-000011	Growth mechanism of (111) copper single crystal growth via heat treatment	LEE CHAN-YOUNG	ULSAN NATIONAL INSTITUTE OF SCIENCE AND TECHNOLOGY (UNIST)
P5-31	ABST-000129	Effect of Cu grain size and reflow Time-Above-Liquidus on interfacial intermetallic compound formation and growth in Sn-3.0Ag-0.5Cu solder joints	JEONG SEON-JU	CHUNGBUK NATIONAL UNIVERSITY
P5-32	ABST-000091	Interfacial Reactions Between ENIG-Finished Cu Substrates and SAC305 Solder Paste Incorporating Gallium Particles	CHOI JUNGHWAN	CHOSUN UNIVERSITY
P5-33	ABST-000089	Interfacial Reactions Between Ga-Particle-Contained Sn–58Bi Solder Paste and ENIG-Finished Substrates	PARK HEESEONG	CHOSUN UNIVERSITY

P5-34		Measurement of thermal conductivity using the thermoreflectance mothod	LEE WONJEONG	KOREA ADVANCED INSTITUTE OF SCIENCE AND TECHNOLOGY (KAIST)
6. Equipment Technology				
P6-01	ABST-000202	Gecko-Inspired Multi-Layer Soft Gripper for Reliable Wafer/Package Handling in Advanced Packaging	CHO SANGMIN	HANYANG UNIVERSITY
7. Metrology and Inspections				
P7-01	ABST-000208	Nondestructive Evaluation of Automotive Semiconductor Packages Using 3D X-ray Computed Tomography	JO EUNBYEOUL	KOREA AUTOMOTIVE TECHNOLOGY INSTITUTE (KATECH)
P7-02	ABST-000178	Fabrication and Characterization of Standardized 8-inch TEG Wafer Kits for Flip-Chip Assembly and Underfill Testing	KIM HYEONSEOL	NATIONAL NANO FAB CENTER (NNFC)
P7-03	ABST-000163	Direct Resistance Measurement of Single Through Glass Via Using Kelvin Probe Method	LEE JUYEON	KOREA ELECTRONICS TECHNOLOGY INSTITUTE (KETI)
P7-04	ABST-000074	Measurement of the total overlay error of a 200 mm wafer-to-wafer hybrid bonding	KIM SEORIN	KOREA ADVANCED NANO FAB CENTER (KANC)
P7-05	ABST-000020	Role of fluorine atoms in micro-electric device: a study of atom probe tomography	CHOI KYEONG-KEUN	POHANG UNIVERSITY OF SCIENCE AND TECHNOLOGY (POSTECH)
P7-06	ABST-000124	Feasibility Study of U-Net Based Wafer Map Classification Enhanced by Morphological Techniques	LEE HYO GI	HOSEO UNIVERSITY
8. Reliability Engineering				
P8-01	ABST-000159	Effect of Chip Layout on Warpage-Induced Delamination in Copper/FR4 Substrates under Mechanical Loading	JU MIN SANG	KOREA ADVANCED INSTITUTE OF SCIENCE AND TECHNOLOGY (KAIST)
P8-02	ABST-000195	Drop impact reliability of SAC Solder: Insights from high strain-rate and elevated-temperature behavior	YOO DONG HOON	HANYANG UNIVERSITY
P8-03	ABST-000193	Thermal Fatigue Characterization of SAC305 Solder Joints via a DNP-Oriented Modified Test Vehicle	PARK HYEONGBIN	HANYANG UNIVERSITY
P8-04	ABST-000151	Prediction of Mechanical Properties of metallic film Using a Machine Learning Model Based on FE Simulation of Nanoindentation	HAM JUBEEN	GYEONGKUK NATIONAL UNIVERSITY
P8-05	ABST-000128	Depth-Dependent Nano-Hardness Assessment of Sputtered Cu Thin Films on Flexible Polyimide with Calibration of Contact Area	SEO HEECHANG	GYEONGKUK NATIONAL UNIVERSITY
P8-06	ABST-000122	Electroplating Current Density Effects on Undercut Formation and Reliability of Cu Pillars for 2.5D/3D Packaging	YOON JAEJUN	SUNGKYUNKWAN UNIVERSITY
P8-07	ABST-000120	Compression-Induced Fracture Behavior and Electrochemical Performance of Secondary Particles in Lithium-Ion Battery Cathodes using Semiconductor Processing	SEO SAE-DEOK	GYEONGKUK NATIONAL UNIVERSITY
P8-08	ABST-000119	Prediction of Elastic Modulus via Nanoindentation-Based FEA and ML: Cu Films on Polyimide Substrates	KIM JIHYEON	GYEONGKUK NATIONAL UNIVERSITY
P8-09	ABST-000116	Prediction of Interfacial Adhesion Energy in Hybrid Bonding Structures Using Nanoindentation-Based Finite Element Analysis	NAM SEO-WOO	GYEONGKUK NATIONAL UNIVERSITY
P8-10	ABST-000099	Development and Evaluation of Micro-DIC Patterning Techniques for Micro-Scale Deformation Analysis of Fine-Pitch Semiconductor Packages	NAM HYUNWOO	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)
P8-11	ABST-000084	Electromigration Behavior of Sn–58Bi Solder Joints Fabricated by Intense Pulsed Light Soldering	GO HYERI	CHOSUN UNIVERSITY
P8-12	ABST-000073	Breakdown Characteristics of Photoimageable Dielectric Films for Semiconductor Packaging	KIM DONG YOUNG	HANYANG UNIVERSITY
P8-13	ABST-000055	Reliability of Fatigue Deformation for Flexible Substrate-Metal Thin Film System Varying Interfacial Adhesion	HEO JEONG A	KUMOH NATIONAL INSTITUTE OF TECHNOLOGY
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P8-15		Effect of Pd Layer Thickness in ENEPIG Surface Finishes on Interfacial Reactions and Mechanical Reliability	JIN HYERIN	SUNGKYUNKWAN UNIVERSITY